

4K

X25043/45

512 x 8 Bit

Programmable Watchdog Supervisory E²PROM

FEATURES

- Programmable Watchdog Timer
- Low V_{CC} Detection
- Reset Signal Valid to V_{CC} = 1V
- 1MHz Clock Rate
- 512 X 8 Bits Serial E²PROM
 - 4 Byte Page Mode
- Low Power CMOS
 - 50µA Standby Current
 - 3mA Active Current
- 2.7V To 5.5V Power Supply
- Block Lock™
 - Protect 1/4, 1/2 or all of E²PROM Array
- Built-in Inadvertent Write Protection
 - Power-Up/Power-Down protection circuitry
 - Write Latch
 - Write Protect Pin
- High Reliability
 - Endurance: 100,000 cycles per byte
 - Data Retention: 100 Years
 - ESD protection: 2000V on all pins
- Available Packages
 - 8-Lead PDIP
 - 8-Lead SOIC
 - 14-Lead TSSOP
- X25043 = Active LOW RESET
- X25045 = Active HIGH RESET

DESCRIPTION

The X25043/45 combines three popular functions, Watchdog Timer, Voltage Supervision, and E²PROM in a single package. This combination lowers the system cost and reduces the board space requirements.

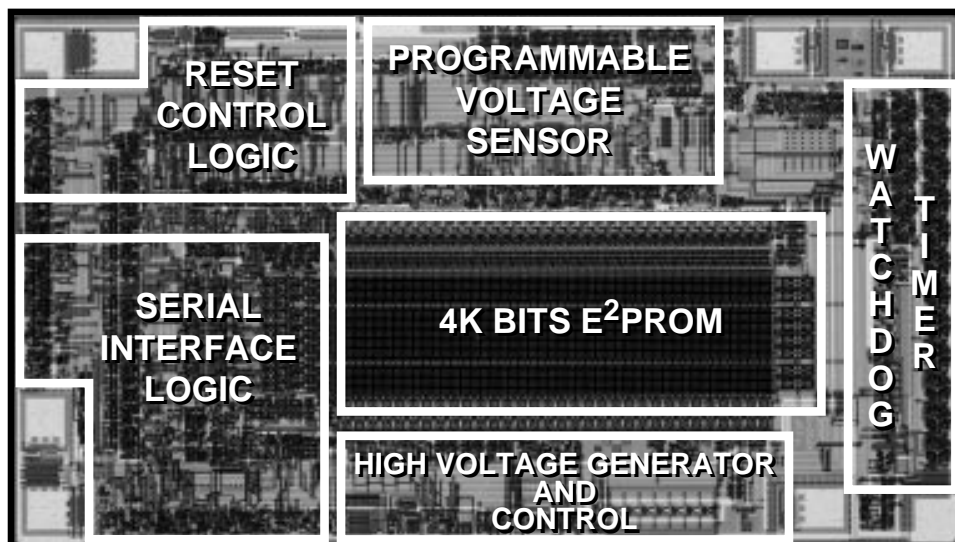
The Watchdog Timer provides an independent protection system for microcontrollers. During a system failure, the X25043/45 watchdog will respond with a RESET/RESET signal after a selectable time-out interval. The user selects the interval from three preset values. Once selected, the interval does not change, even after cycling the power.

The system is protected from low voltage conditions by the X25043/45 low V_{CC} detection circuits. When V_{CC} drops below the minimum V_{CC} trip point, the system is reset. Reset is asserted until V_{CC} returns and stabilizes.

The memory portion of the X25043/45 is a CMOS 4096-bit serial E²PROM, internally organized as 512 X 8. The X25043/45 features a Serial Peripheral Interface (SPI) and software protocol allowing operation on a simple three-wire bus.

The X25043/45 utilizes Xicor's proprietary Direct Write™ cell, providing a minimum endurance of 100,000 cycles per byte and a minimum data retention of 100 years.

DIE PHOTOGRAPH



X25043/45

PIN DESCRIPTIONS

Serial Output (SO)

SO is a push/pull serial data output pin. During a read cycle, data is shifted out on this pin. Data is clocked out by the falling edge of the serial clock.

Serial Input (SI)

SI is the serial data input pin. All opcodes, byte addresses, and data to be written to the memory are input on this pin. Data is latched by the rising edge of the serial clock.

Serial Clock (SCK)

The Serial Clock controls the serial bus timing for data input and output. Opcodes, addresses, or data present on the SI pin is latched on the rising edge of the clock input, while data on the SO pin changes after the falling edge of the clock input.

Chip Select (\overline{CS})

When \overline{CS} is HIGH, the X25043/45 is deselected and the SO output pin is at high impedance and, unless an internal write operation is underway, the X25043/45 will be in the standby power mode. \overline{CS} LOW enables the X25043/45, placing it in the active power mode. It should be noted that after power-up, a HIGH to LOW transition on \overline{CS} is required prior to the start of any operation.

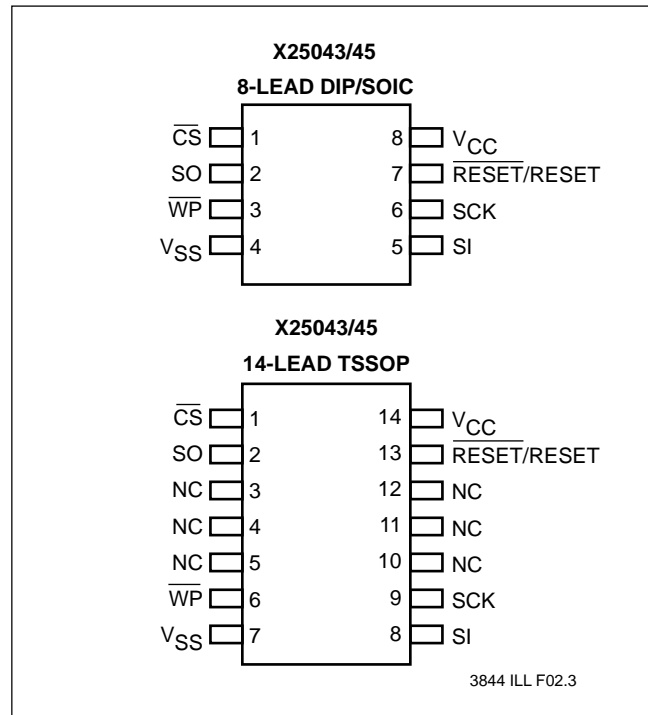
Write Protect (\overline{WP})

When \overline{WP} is LOW, nonvolatile writes to the X25043/45 are disabled, but the part otherwise functions normally. When \overline{WP} is held HIGH, all functions, including nonvolatile writes operate normally. \overline{WP} going LOW while \overline{CS} is still LOW will interrupt a write to the X25043/45. If the internal write cycle has already been initiated, \overline{WP} going LOW will have no affect on a write.

Reset (\overline{RESET} , RESET)

X25043/45, \overline{RESET} /RESET is an active LOW/HIGH, open drain output which goes active whenever V_{CC} falls below the minimum V_{CC} sense level. It will remain active until V_{CC} rises above the minimum V_{CC} sense level for 200ms. \overline{RESET} /RESET also goes active if the Watchdog timer is enabled and \overline{CS} remains either HIGH or LOW longer than the Watchdog time-out period. A falling edge of \overline{CS} will reset the watchdog timer.

PIN CONFIGURATION



PIN NAMES

| Symbol | Description |
|---------------------------|---------------------|
| \overline{CS} | Chip Select Input |
| SO | Serial Output |
| SI | Serial Input |
| SCK | Serial Clock Input |
| \overline{WP} | Write Protect Input |
| V_{SS} | Ground |
| V_{CC} | Supply Voltage |
| \overline{RESET} /RESET | Reset Output |

3844 PGM T01.1

X25043/45

PRINCIPLES OF OPERATION

The X25043/45 is a 512 x 8 E²PROM designed to interface directly with the synchronous serial peripheral interface (SPI) of many popular microcontroller families.

The X25043/45 contains an 8-bit instruction register. It is accessed via the SI input, with data being clocked in on the rising SCK. \overline{CS} must be LOW and \overline{WP} input must be HIGH during the entire operation. The X25043/45 monitors the bus and provides a $\overline{RESET}/RESET$ output if there is no bus activity within the preset time period.

Table 1 contains a list of the instructions and their operation codes. All instructions, addresses and data are transferred MSB first. Bit 3 of the Read and Write instructions contain the higher order address bit, A₈.

Data input is sampled on the first rising edge of SCK after \overline{CS} goes LOW. SCK is static, allowing the user to stop the clock and then resume operations.

Write Enable Latch

The X25043/45 contains a “write enable” latch. This latch must be SET before a write operation will be completed internally. The WREN instruction will set the latch and the WRDI instruction will reset the latch. This latch is automatically reset upon a power-up condition and after the completion of a byte, page, or status register write cycle. The latch is also reset if \overline{WP} is brought LOW.

Status Register

The RDSR instruction provides access to the status register. The status register may be read at any time, even during a write cycle. The status register is formatted as follows:

| | | | | | | | |
|---|---|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| X | X | WD1 | WD0 | BL1 | BL0 | WEL | WIP |

3844 PGM T02

When issuing, WREN, WRDI and RDSR commands, it is not necessary to send a byte address or data.

The Write-In-Process (WIP) bit indicates whether the X25043/45 is busy with a write operation. When set to a “1”, a write is in progress, when set to a “0”, no write is in progress. During a write, all other bits are set to “1”. The WIP bit is read-only.

The Write Enable Latch (WEL) bit indicates the status of the “write enable” latch. When set to a “1”, the latch is set, when set to a “0”, the latch is reset. The WEL bit is read-only and is set by the WREN instruction and reset by WRDI instruction or successful completion of a write cycle.

The Block Protect (BL0 and BL1) bits indicate the extent of protection employed. These nonvolatile bits are set by issuing the WRSR instruction and allows the user to select one of four levels of protection and program the watchdog timer. The X25043/45 is divided into four 1024-bit segments. One, two, or all four of the segments may be locked. That is, the user may read the segments but will be unable to alter (write) data within the selected segments. The partitioning is controlled as illustrated below with the state of BL1 and BL0.

| Status Register Bits | | Array Addresses Protected |
|----------------------|-----|---------------------------|
| BL1 | BL0 | |
| 0 | 0 | None |
| 0 | 1 | \$180–\$1FF |
| 1 | 0 | \$100–\$1FF |
| 1 | 1 | \$000–\$1FF |

3844 PGM T04

The Watchdog Timer (WD0 and WD1) bits allow setting of the watchdog time-out function as shown in the table below. These nonvolatile bits are set by issuing the WRSR instruction.

| Status Register Bits | | Watchdog Time-out (Typical) |
|----------------------|-----|-----------------------------|
| WD1 | WD0 | |
| 0 | 0 | 1.4 Seconds |
| 0 | 1 | 600 Milliseconds |
| 1 | 0 | 200 Milliseconds |
| 1 | 1 | Disabled |

3844 PGM T03

X25043/45

Clock and Data Timing

Data input on the SI line is latched on the rising edge of SCK. Data is output on the SO line by the falling edge of SCK.

Read Sequence

When reading from the E²PROM memory array, \overline{CS} is first pulled LOW to select the device. The 8-bit READ instruction is transmitted to the X25043/45, followed by the 8-bit byte address. Bit 3 of the Read instruction contains address A₈. This bit is used to select the upper or lower half of the device. After the read opcode and byte address are sent, the data stored in the memory at the selected address is shifted out on the SO line. The data stored in memory at the next address can be read sequentially by continuing to provide clock pulses. The byte address is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (\$1FF) the address counter rolls over to address \$000, allowing the read cycle to be continued indefinitely. The read operation is terminated by taking \overline{CS} HIGH. Refer to the read E²PROM Array operation sequence illustrated in Figure 1.

To read the status register the \overline{CS} line is first pulled LOW to select the device followed by the 8-bit RDSR instruction. After the read status register opcode is sent, the contents of the status register is shifted out on the SO line as shown in Figure 2.

Write Sequence

Prior to any attempt to write data into the X25043/45 the “write enable” latch must first be set by issuing the WREN instruction (See Figure 3). \overline{CS} is first taken LOW, then the WREN instruction is clocked into the X25043/45. After all eight bits of the instruction are

transmitted, \overline{CS} must then be taken HIGH. If the user continues the write operation without taking \overline{CS} HIGH after issuing the WREN instruction the write operation will be ignored.

To write data to the E²PROM memory array, the user issues the WRITE instruction, followed by the address and then the data to be written. Bit 3 of the Write instruction contains address A₈. This bit is used to select the upper or lower half of the device. This is minimally a twenty-four clock operation. \overline{CS} must go LOW and remain LOW for the duration of the operation. The host may continue to write up to four bytes of data to the X25043/45. The only restriction is the four bytes must reside on the same page. A page address begins with address X XXXX XX00 and ends with X XXXX XX11. If the byte address counter reaches X XXXX XX11 and the clock continues the counter will roll back to the first address of the page and overwrite any data that may have been written.

For the write operation (byte or page write) to be completed, \overline{CS} can only be brought HIGH after the twenty-fourth, thirty-second, fortieth, or forty-eighth clock. If it is brought HIGH at any other time, the write operation will not be completed. Refer to Figure 4 and 5 below for a detailed illustration of the write sequences.

While the write is in progress, following a status register or E²PROM write sequence the status register may be read to check the WIP bit. During this time the WIP bit will be HIGH and all other bits in the status register will be undefined.

\overline{RESET} /RESET Operation

The \overline{RESET} (X25043) output is designed to go LOW whenever V_{CC} has dropped below the minimum trip point and/or the Watchdog timer has reached its programmable time-out limit.

Table 1. Instruction Set

| Instruction Name | Instruction Format* | Operation |
|------------------|-------------------------|---|
| WREN | 0000 0110 | Set the Write Enable Latch (Enable Write Operations) |
| WRDI | 0000 0100 | Reset the Write Enable Latch (Disable Write Operations) |
| RDSR | 0000 0101 | Read Status Register |
| WRSR | 0000 0001 | Write Status Register (Block Lock Bits) |
| READ | 0000 A ₈ 011 | Read Data from Memory Array beginning at selected address |
| WRITE | 0000 A ₈ 010 | Write Data to Memory Array beginning at Selected Address (1 to 4 Bytes) |

*Instructions are shown MSB in leftmost position. Instructions are transferred MSB first.

X25043/45

The RESET (X25045) output is designed to go HIGH whenever V_{CC} has dropped below the minimum trip point and/or the watchdog timer has reached its programmable time-out limit.

Operational Notes

The X25043/45 powers-up in the following state:

- The device is in the low power standby state.
- A HIGH to LOW transition on \overline{CS} is required to enter an active state and receive an instruction.
- SO pin is high impedance.
- The “write enable” latch is reset.

Data Protection

The following circuitry has been included to prevent inadvertent writes:

- The “write enable” latch is reset upon power-up.
- A WREN instruction must be issued to set the “write enable” latch.
- \overline{CS} must come HIGH at the proper clock count in order to start a write cycle.

The “write enable” latch is reset when \overline{WP} is brought LOW.

Figure 1. Read E²PROM Array Operation Sequence

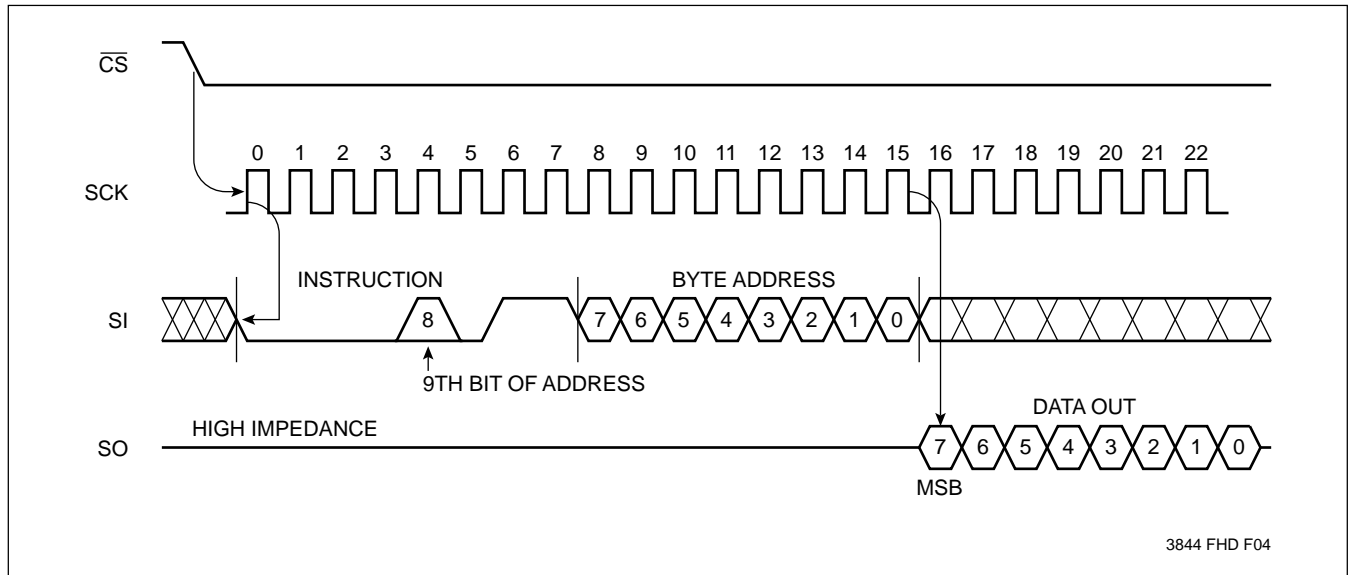


Figure 2. Read Status Register Operation Sequence

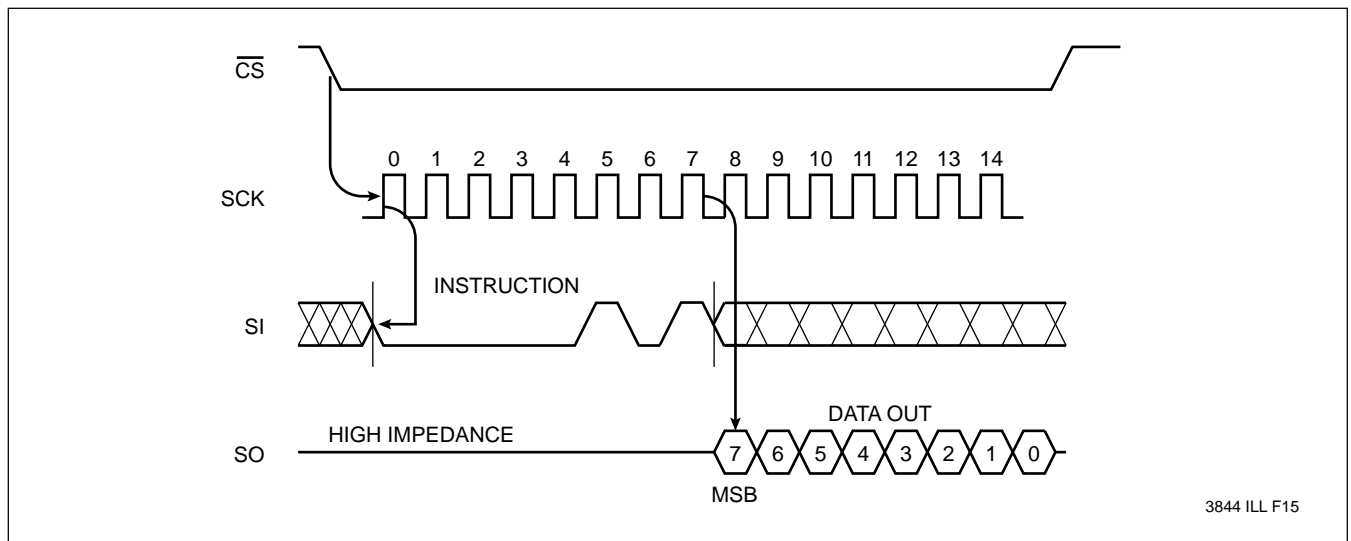


Figure 3. Write Enable Latch Sequence

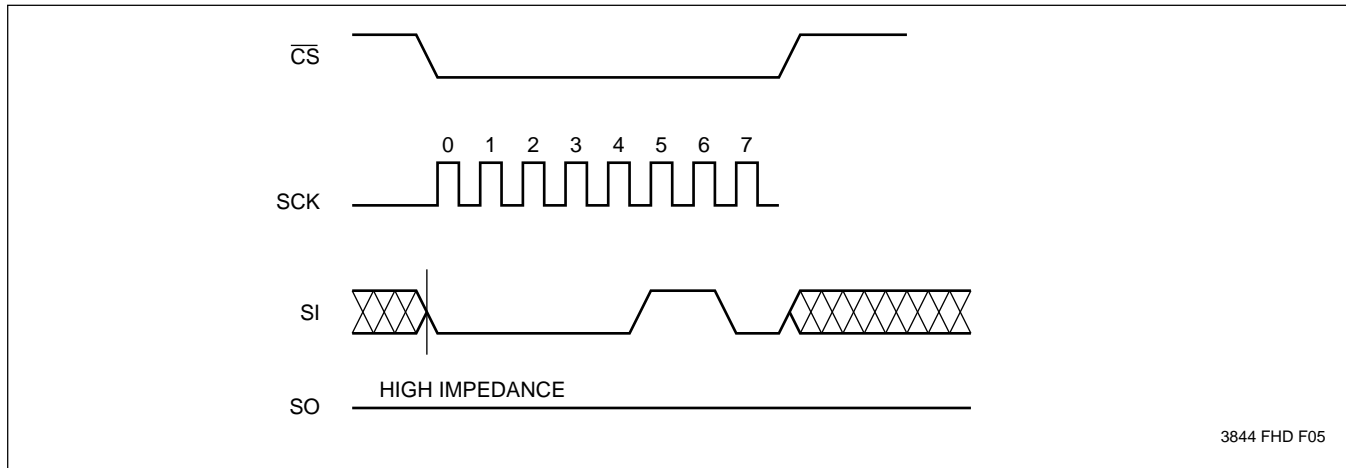
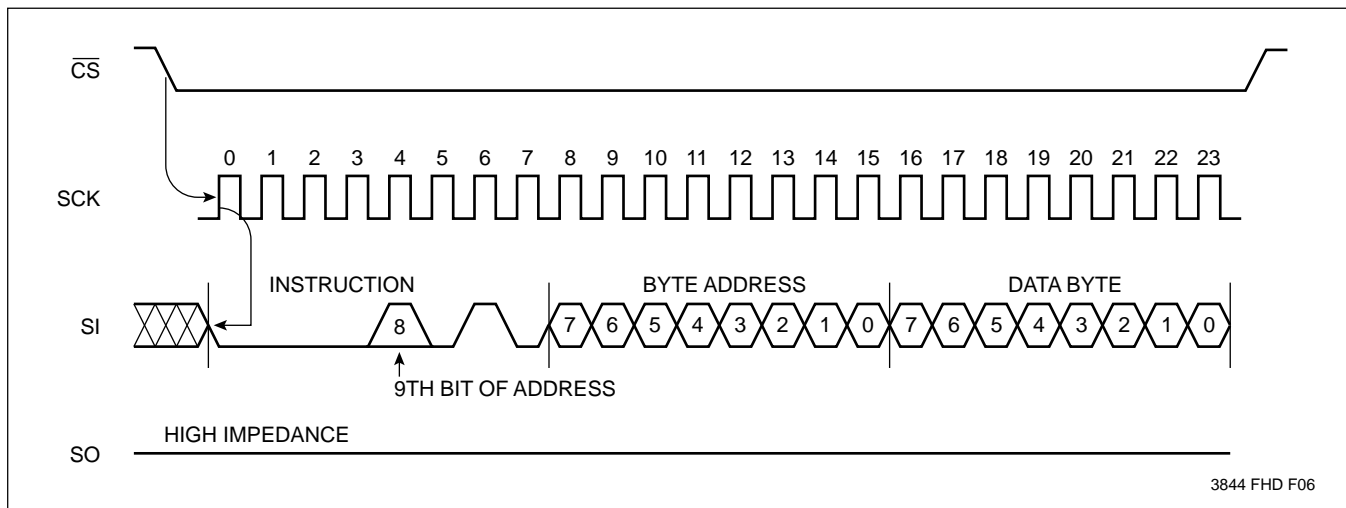


Figure 4. Byte Write Operation Sequence



SYMBOL TABLE

| WAVEFORM | INPUTS | OUTPUTS |
|----------|-----------------------------|-------------------------------|
| | Must be steady | Will be steady |
| | May change from LOW to HIGH | Will change from LOW to HIGH |
| | May change from HIGH to LOW | Will change from HIGH to LOW |
| | Don't Care: Changes Allowed | Changing: State Not Known |
| | N/A | Center Line is High Impedance |

Figure 5. Page Write Operation Sequence

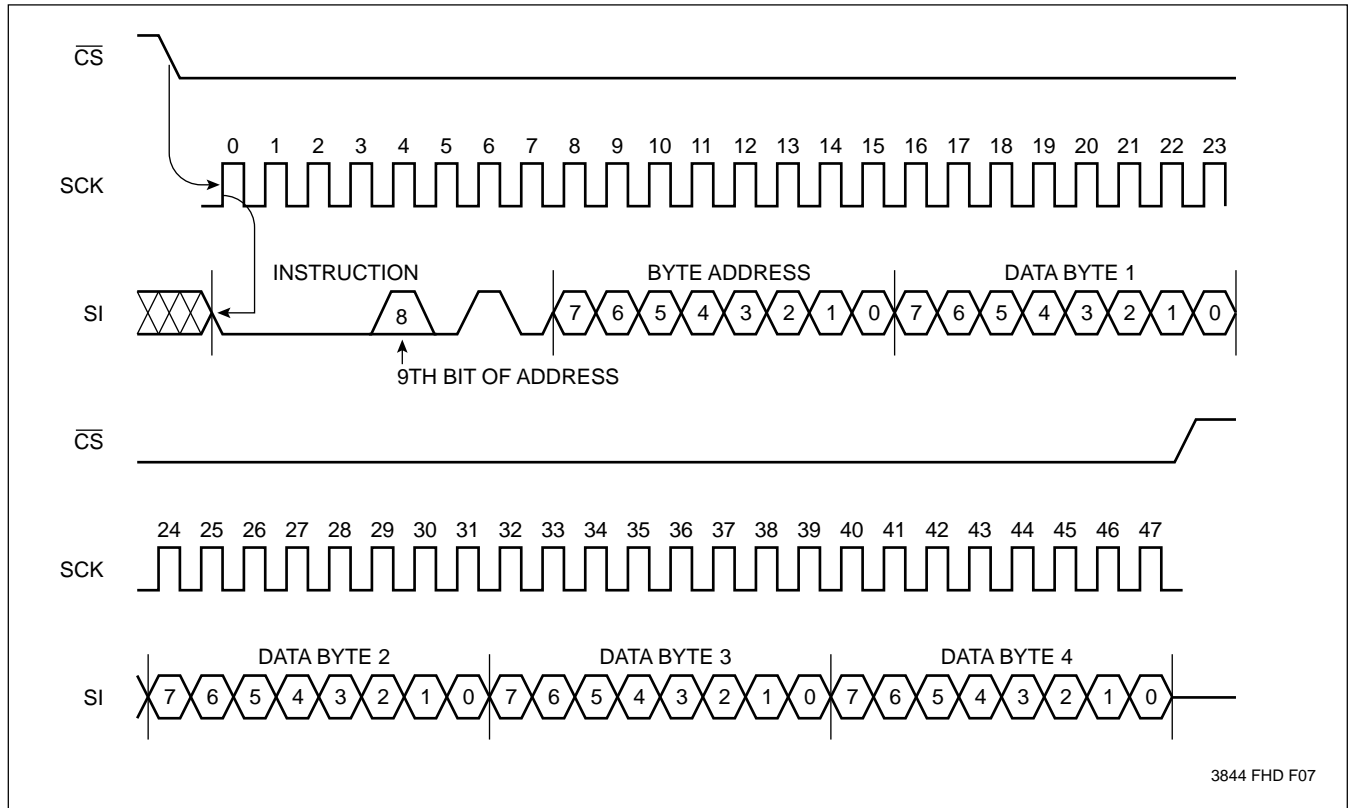
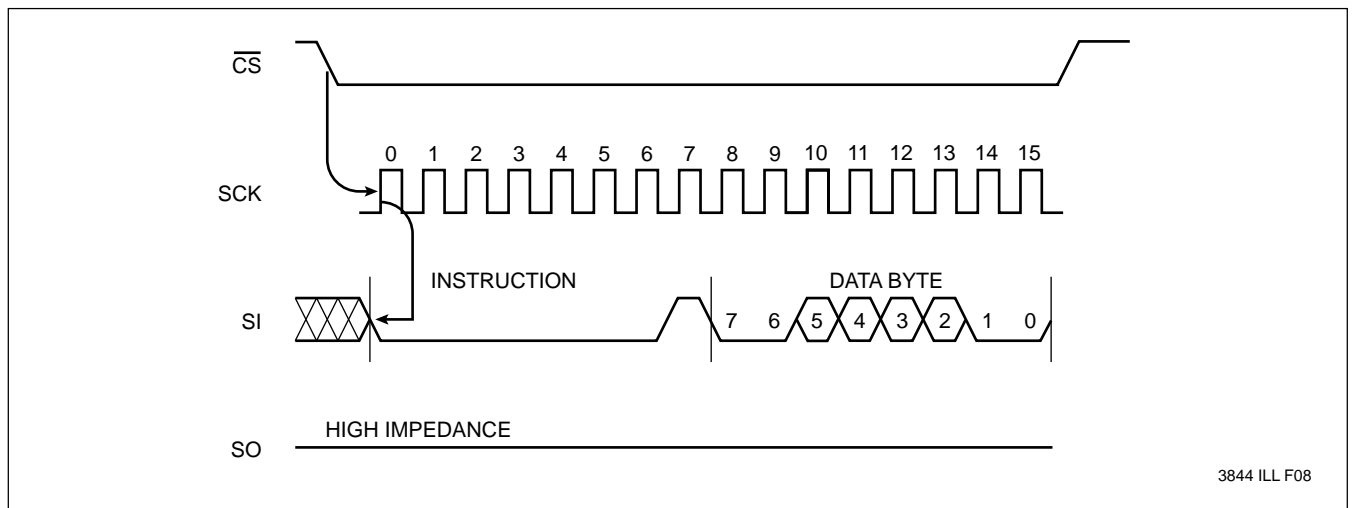


Figure 6. Write Status Register Operation Sequence



X25043/45

ABSOLUTE MAXIMUM RATINGS*

| | |
|--|-----------------|
| Temperature under Bias | -65°C to +135°C |
| Storage Temperature | -65°C to +150°C |
| Voltage on any Pin with Respect to V _{SS} | -1.0V to +7V |
| D.C. Output Current | 5mA |
| Lead Temperature | |
| (Soldering, 10 seconds) | 300°C |

*COMMENT

Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and the functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

| Temp | Min. | Max. |
|------------|-------|-------|
| Commercial | 0°C | 70°C |
| Industrial | -40°C | +85°C |

3844 PGM T06.1

| Supply Voltage | Limits |
|----------------|-------------|
| X25043/45 | 5V ±10% |
| X25043/45-2.7 | 2.7 to 5.5V |

3844 PGM T07.3

D.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions unless otherwise specified.)

| Symbol | Parameter | Limits | | Units | Test Conditions |
|--------------------------------|---|-----------------------|-----------------------|-------|--|
| | | Min. | Max. | | |
| I _{CC} | V _{CC} Supply Current (Active) | | 3 | mA | SCK = V _{CC} x 0.1/V _{CC} x 0.9 @ 1MHz, SO = Open |
| I _{SB1} | V _{CC} Standby Current | | 50 | µA | $\overline{CS} = V_{CC}$, V _{IN} = V _{SS} or V _{CC} , V _{CC} = 5.5 |
| I _{SB2} | V _{CC} Standby Current | | 20 | µA | $\overline{CS} = V_{CC}$, V _{IN} = V _{SS} or V _{CC} , V _{CC} = 2.7V |
| I _{LI} | Input Leakage Current | | 10 | µA | V _{IN} = V _{SS} to V _{CC} |
| I _{LO} | Output Leakage Current | | 10 | µA | V _{OUT} = V _{SS} to V _{CC} |
| V _{IL} ⁽¹⁾ | Input LOW Voltage | -0.5 | V _{CC} x 0.3 | V | |
| V _{IH} ⁽¹⁾ | Input HIGH Voltage | V _{CC} x 0.7 | V _{CC} + 0.5 | V | |
| V _{OL} | Output LOW Voltage | | 0.4 | V | I _{OL} = 2mA |
| V _{OH1} | Output HIGH Voltage | V _{CC} -0.8 | | V | I _{OH} = -1.6mA, V _{CC} = 4.5V |
| V _{OH2} | Output HIGH Voltage | V _{CC} -0.4 | | V | I _{OH} = -.4mA, V _{CC} = 2.7V |
| V _{OLRS} | Reset Output LOW Voltage | | 0.4 | V | I _{OL} = 1mA |

3844 PGM T08.3

POWER-UP TIMING

| Symbol | Parameter | Min. | Max. | Units |
|---------------------------------|-----------------------------|------|------|-------|
| t _{PUR} ⁽²⁾ | Power-up to Read Operation | | 1 | ms |
| t _{PUW} ⁽²⁾ | Power-up to Write Operation | | 5 | ms |

3844 PGM T09

CAPACITANCE T_A = +25°C, f = 1MHz, V_{CC} = 5V.

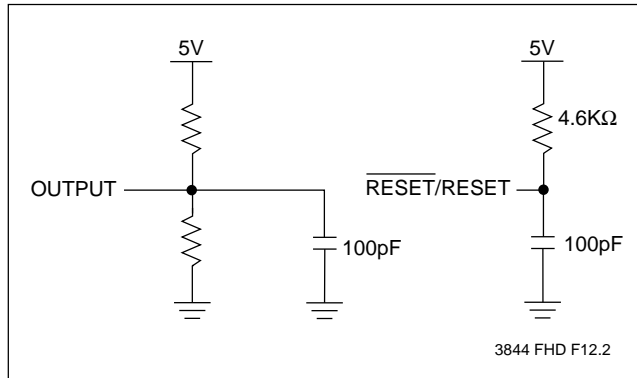
| Symbol | Test | Max. | Units | Conditions |
|---------------------------------|---|------|-------|-----------------------|
| C _{OUT} ⁽²⁾ | Output Capacitance (SO, \overline{RESET} , RESET) | 8 | pF | V _{OUT} = 0V |
| C _{IN} ⁽²⁾ | Input Capacitance (SCK, SI, \overline{CS} , \overline{WP}) | 6 | pF | V _{IN} = 0V |

Notes: (1) V_{IL} min. and V_{IH} max. are for reference only and are not tested.
 (2) This parameter is periodically sampled and not 100% tested.

3844 PGM T10.2

X25043/45

EQUIVALENT A.C. LOAD CIRCUIT AT 5V VCC



A.C. TEST CONDITIONS

| | |
|-------------------------------|--|
| Input Pulse Levels | $V_{CC} \times 0.1$ to $V_{CC} \times 0.9$ |
| Input Rise and Fall Times | 10ns |
| Input and Output Timing Level | $V_{CC} \times 0.5$ |

3844 PGM T11

A.C. CHARACTERISTICS (Over recommended operating conditions, unless otherwise specified)

Data Input Timing

| Symbol | Parameter | Min. | Max. | Units |
|----------------|-------------------------------|------|------|---------|
| f_{SCK} | Clock Frequency | 0 | 1 | MHz |
| t_{CYC} | Cycle Time | 1000 | | ns |
| t_{LEAD} | \overline{CS} Lead Time | 500 | | ns |
| t_{LAG} | \overline{CS} Lag Time | 500 | | ns |
| t_{WH} | Clock HIGH Time | 500 | | ns |
| t_{WL} | Clock LOW Time | 400 | | ns |
| t_{SU} | Data Setup Time | 100 | | ns |
| t_H | Data Hold Time | 100 | | ns |
| $t_{RI}^{(3)}$ | Input Rise Time | | 2 | μs |
| $t_{FI}^{(3)}$ | Input Fall Time | | 2 | μs |
| t_{CS} | \overline{CS} Deselect Time | 500 | | ns |
| $t_{WC}^{(4)}$ | Write Cycle Time | | 10 | ms |

3844 PGM T12.2

Data Output Timing

| Symbol | Parameter | Min. | Max. | Units |
|----------------|-----------------------------|------|------|-------|
| f_{SCK} | Clock Frequency | 0 | 1 | MHz |
| t_{DIS} | Output Disable Time | | 500 | ns |
| t_V | Output Valid from Clock LOW | | 400 | ns |
| t_{HO} | Output Hold Time | 0 | | ns |
| $t_{RO}^{(3)}$ | Output Rise Time | | 300 | ns |
| $t_{FO}^{(3)}$ | Output Fall Time | | 300 | ns |

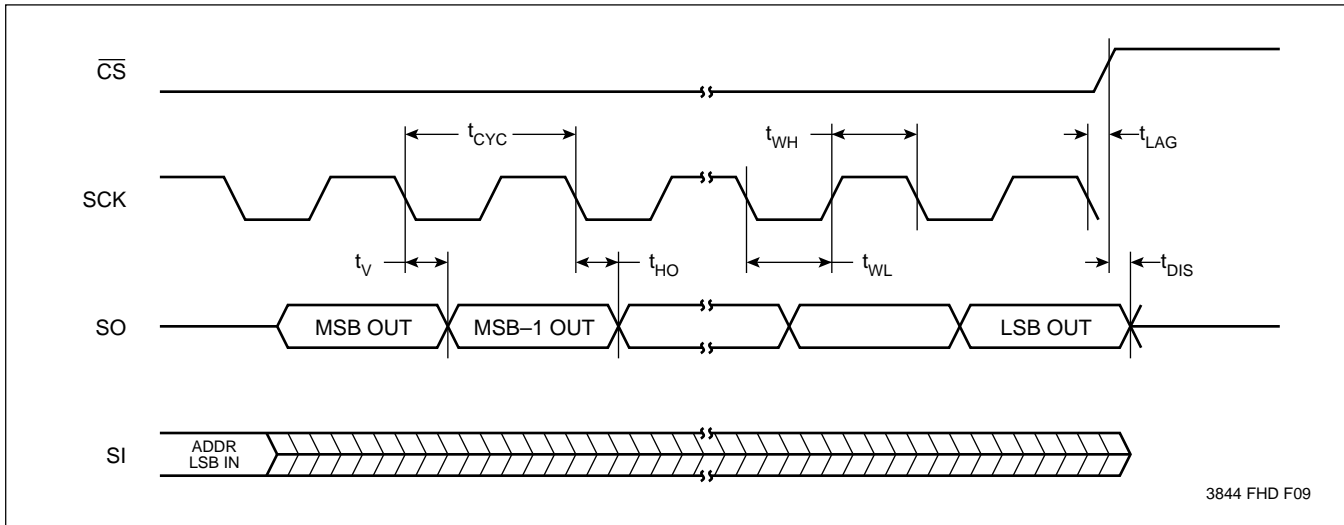
3844 PGM T13.1

Notes: (3) This parameter is periodically sampled and not 100% tested.

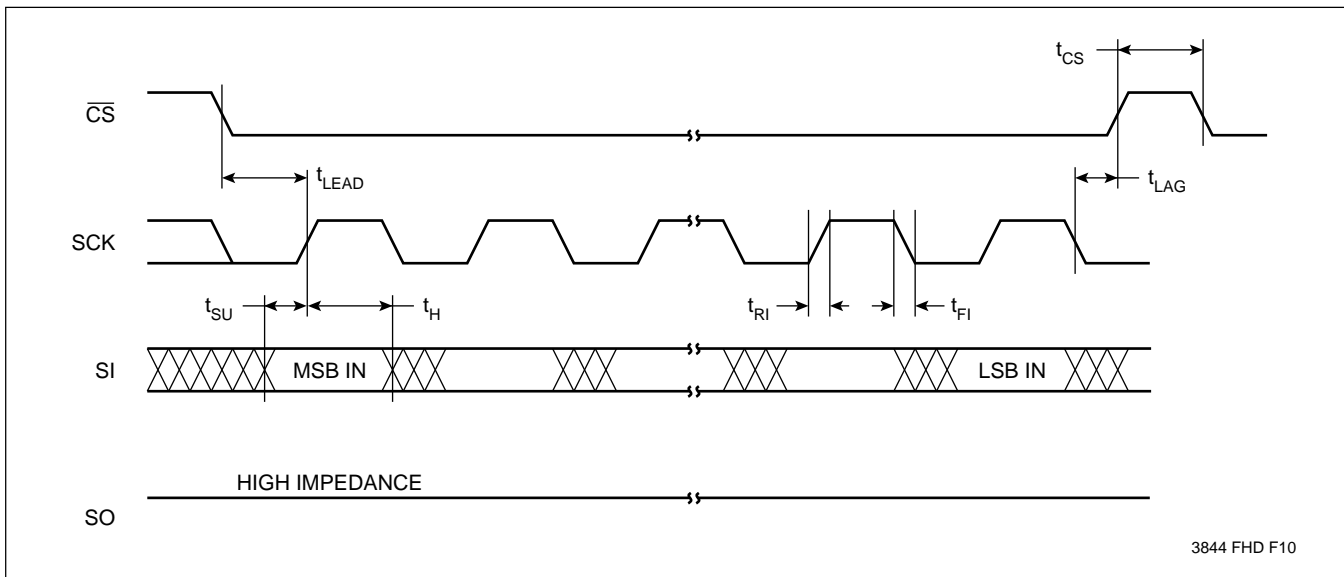
(4) t_{WC} is the time from the rising edge of \overline{CS} after a valid write sequence has been sent to the end of the self-timed internal nonvolatile write cycle.

X25043/45

Serial Output Timing

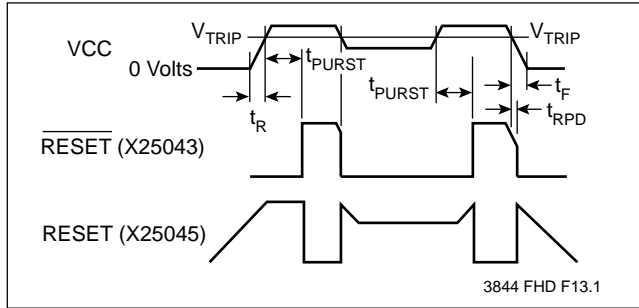


Serial Input Timing



X25043/45

Power-Up and Power-Down Timing



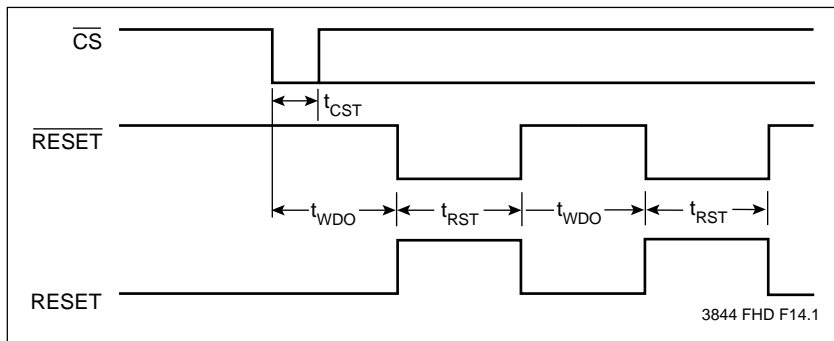
RESET Output Timing

| Symbol | Parameter | Min. | Typ. | Max. | Units |
|---------------------|--|--------------|------|------------|-------|
| V _{TRIP} | Reset Trip Point Voltage, 5V Device Reset Trip Point Voltage, 2.7V Device | 4.25 2.55 | | 4.5 2.7 | V |
| t _{PURST} | Power-up Reset Timeout | 100 | | 400 | ms |
| t _{RPD(5)} | V _{CC} Detect to Reset/Output | | | 500 | ns |
| t _{F(5)} | V _{CC} Fall Time | 10 | | | μs |
| t _{R(5)} | V _{CC} Rise Time | 0 | | | ns |
| V _{RVALID} | Reset Valid V _{CC} | 1 | | | V |

3844 PGM T14.3

Notes: (5) This parameter is periodically sampled and not 100% tested.

CS vs RESET/RESET Timing



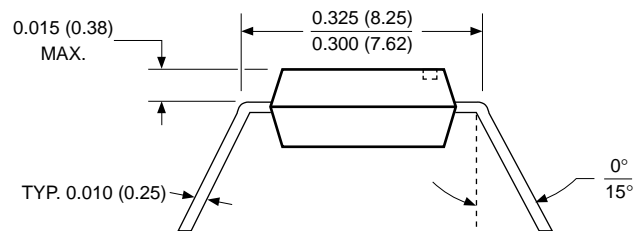
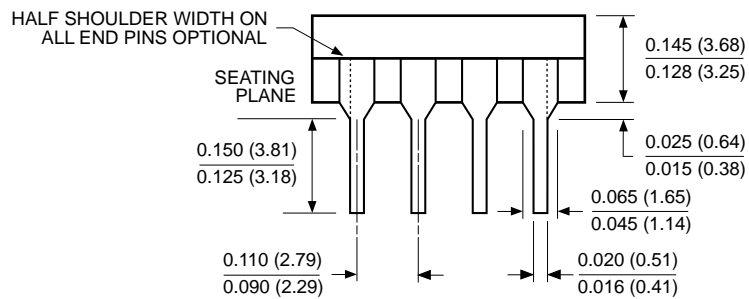
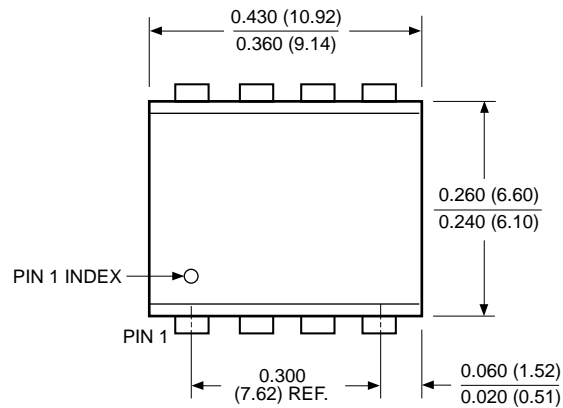
RESET/RESET Output Timing

| Symbol | Parameter | Min. | Typ. | Max. | Units |
|------------------|---|-----------------|-------------------|-----------------|-----------------|
| t _{WDO} | Watchdog Timeout Period, WD1=1,WD0=0 WD1=0,WD0=1 WD1=0,WD0=0 | 100 450 1 | 200 600 1.4 | 300 800 2 | ms ms sec |
| t _{CST} | CS Pulse Width to Reset the Watchdog | 400 | | | ns |
| t _{RST} | Reset Timeout | 100 | | 400 | ms |

3844 PGM T15.3

PACKAGING INFORMATION

8-LEAD PLASTIC DUAL IN-LINE PACKAGE TYPE P



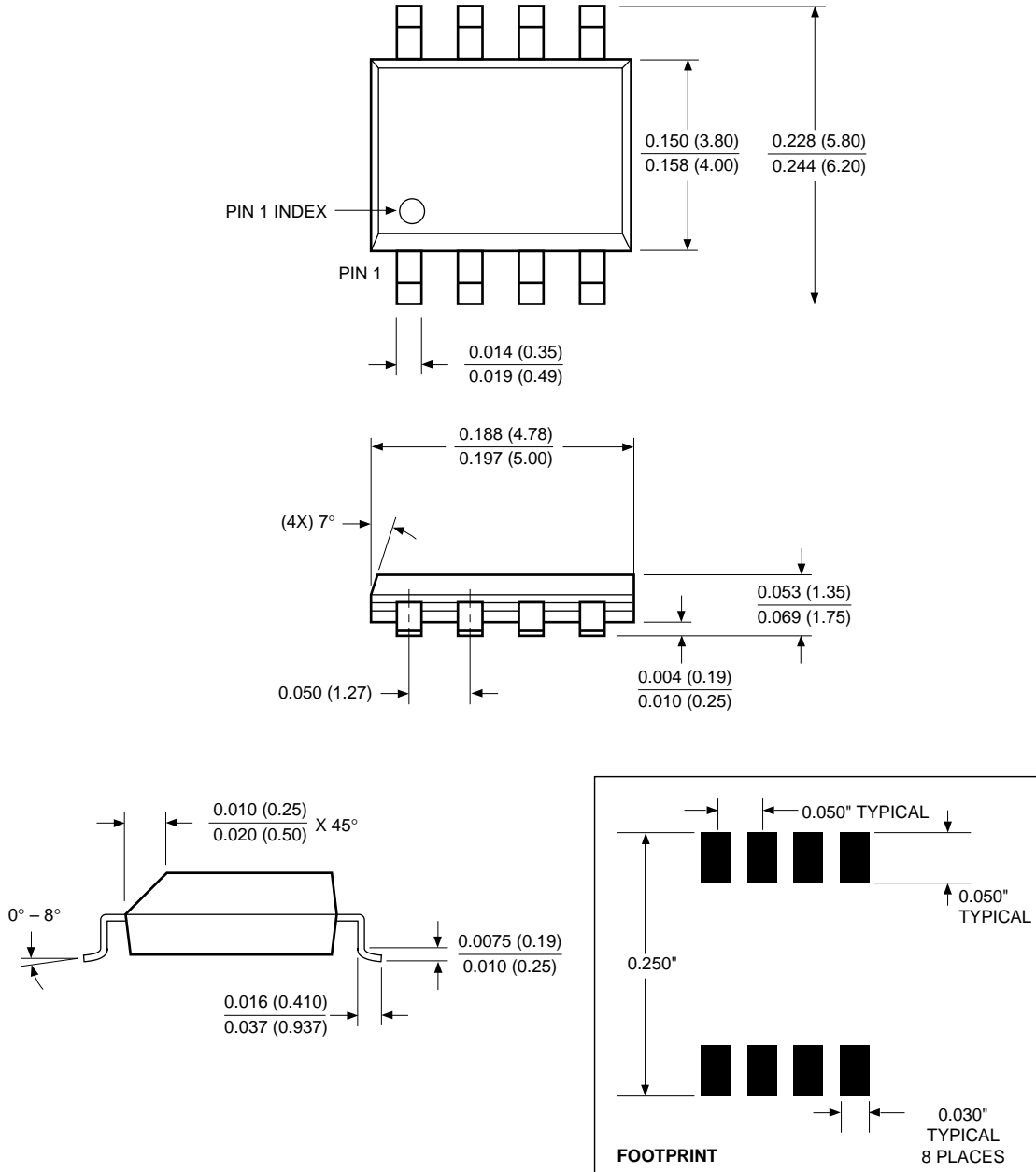
NOTE:

1. ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)
2. PACKAGE DIMENSIONS EXCLUDE MOLDING FLASH

X25043/45

PACKAGING INFORMATION

8-LEAD PLASTIC SMALL OUTLINE GULL WING PACKAGE TYPE S

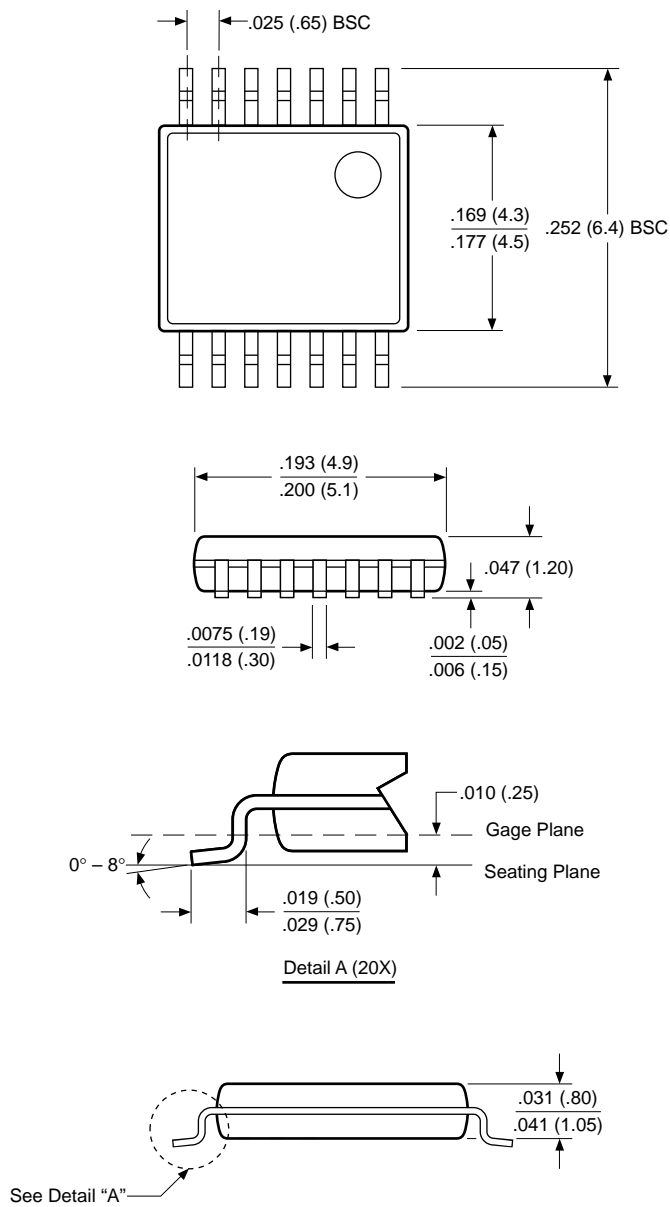


NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

X25043/45

PACKAGING INFORMATION

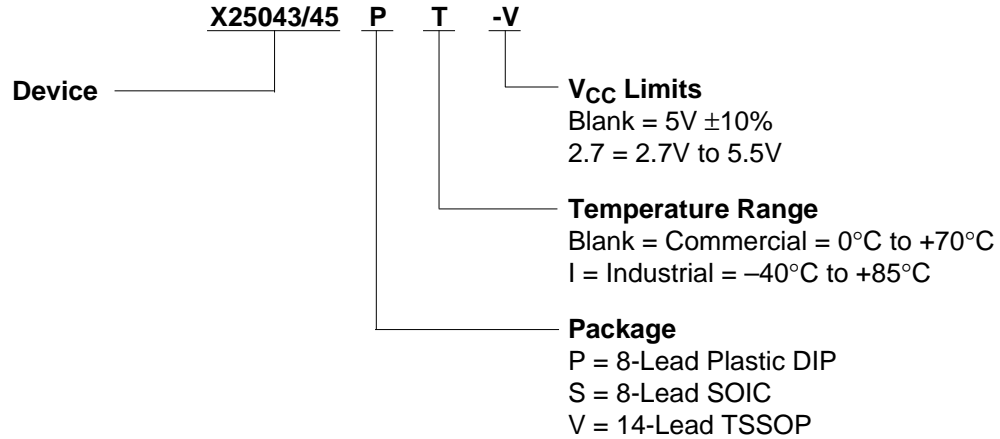
14-LEAD PLASTIC, TSSOP PACKAGE TYPE V



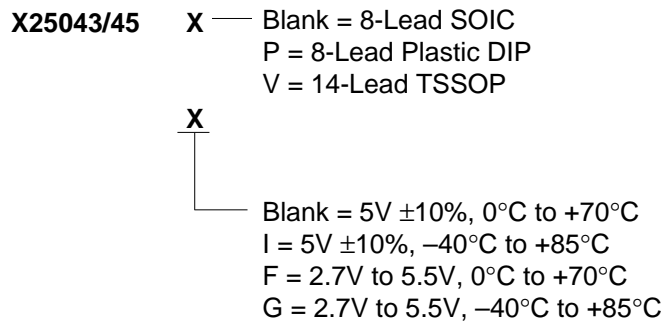
NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

X25043/45

ORDERING INFORMATION



Part Mark Convention



LIMITED WARRANTY

Devices sold by Xicor, Inc. are covered by the warranty and patent indemnification provisions appearing in its Terms of Sale only. Xicor, Inc. makes no warranty, express, statutory, implied, or by description regarding the information set forth herein or regarding the freedom of the described devices from patent infringement. Xicor, Inc. makes no warranty of merchantability or fitness for any purpose. Xicor, Inc. reserves the right to discontinue production and change specifications and prices at any time and without notice.

Xicor, Inc. assumes no responsibility for the use of any circuitry other than circuitry embodied in a Xicor, Inc. product. No other circuits, patents, licenses are implied.

U.S. PATENTS

Xicor products are covered by one or more of the following U.S. Patents: 4,263,664; 4,274,012; 4,300,212; 4,314,265; 4,326,134; 4,393,481; 4,404,475; 4,450,402; 4,486,769; 4,488,060; 4,520,461; 4,533,846; 4,599,706; 4,617,652; 4,668,932; 4,752,912; 4,829,482; 4,874,967; 4,883,976. Foreign patents and additional patents pending.

LIFE RELATED POLICY

In situations where semiconductor component failure may endanger life, system designers using this product should design the system with appropriate error detection and correction, redundancy and back-up features to prevent such an occurrence.

Xicor's products are not authorized for use in critical components in life support devices or systems.

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.
-

X25043/45

U.S. SALES OFFICES

Corporate Office

Xicor Inc.
1511 Buckeye Drive
Milpitas, CA 95035
Phone: 408/432-8888
Fax: 408/432-0640
E-mail: info@smtpgate.xicor.com

Northeast Region

Xicor Inc.
1344 Main Street
Waltham, MA 02154
Phone: 617/899-5510
Fax: 617/899-6808
E-mail: xicor-ne@smtpgate.xicor.com

Southeast Region

Xicor Inc.
100 E. Sybelia Ave.
Suite 355
Maitland, FL 32751
Phone: 407/740-8282
Fax: 407/740-8602
E-mail: xicor-se@smtpgate.xicor.com

Mid-Atlantic Region

Xicor Inc.
50 North Street
Danbury, CT 06810
Phone: 203/743-1701
Fax: 203/794-9501
E-mail: xicor-ma@smtpgate.xicor.com

North Central Region

Xicor Inc.
810 South Bartlett Road
Suite 103
Streamwood, IL 60107
Phone: 708/372-3200
Fax: 708/372-3210
E-mail: xicor-nc@smtpgate.xicor.com

South Central Region

Xicor Inc.
11884 Greenville Ave.
Suite 102
Dallas, TX 75243
Phone: 214/669-2022
Fax: 214/644-5835
E-mail: xicor-sc@smtpgate.xicor.com

Southwest Region

Xicor Inc.
4100 Newport Place Drive
Suite 710
Newport Beach, CA 92660
Phone: 714/752-8700
Fax: 714/752-8634
E-mail: xicor-sw@smtpgate.xicor.com

Northwest Region

Xicor Inc.
2700 Augustine Drive
Suite 219
Santa Clara, CA 95054
Phone: 408/292-2011
Fax: 408/980-9478
E-mail: xicor-nw@smtpgate.xicor.com

INTERNATIONAL SALES OFFICES

EUROPE

Northern Europe

Xicor Ltd.
Grant Thornton House
Witan Way
Witney
Oxford OX8 6FE
UK
Phone: (44) 1933.700544
Fax: (44) 1933.700533
E-mail: xicor-uk@smtpgate.xicor.com

Central Europe

Xicor GmbH
Technopark Neukeferloh
Bretonischer Ring 15
85630 Grasbrunn bei Muenchen
Germany
Phone: (49) 8946.10080
Fax: (49) 8946.05472
E-mail: xicor-gm@smtpgate.xicor.com

ASIA/PACIFIC

Japan

Xicor Japan K.K.
Suzuki Building, 4th Floor
1-6-8 Shinjuku, Shinjuku-ku
Tokyo 160, Japan
Phone: (81) 3322.52004
Fax: (81) 3322.52319
E-mail: xicor-jp@smtpgate.xicor.com

Mainland China

Taiwan/Hong Kong

Xicor Inc.
4100 Newport Place Drive
Suite 710
Newport Beach, CA 92660
Phone: 714/752-8700
Fax: 714/752-8634
E-mail: xicor-sw@smtpgate.xicor.com

Singapore/Malaysia/India

Xicor Inc.
2700 Augustine Drive
Suite 219
Santa Clara, CA 95054
Phone: 408/292-2011
Fax: 408/980-9478
E-mail: xicor-nw@smtpgate.xicor.com

Korea

Xicor Korea
27th Fl., Korea World Trade Ctr.
159, Samsung-dong
Kangnam Ku
Seoul 135-729
Korea
Phone: (82) 2551.2750
Fax: (82) 2551.2710
E-mail: xicor-ka@smtpgate.xicor.com

() = Country Code

Xicor product information is available at:

<http://www.xicor.com>